

FEATURES

- Member of the Texas Instruments Widebus™ Family
- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 3 ns at 3.3 V
- ± 24 -mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

DESCRIPTION/ORDERING INFORMATION

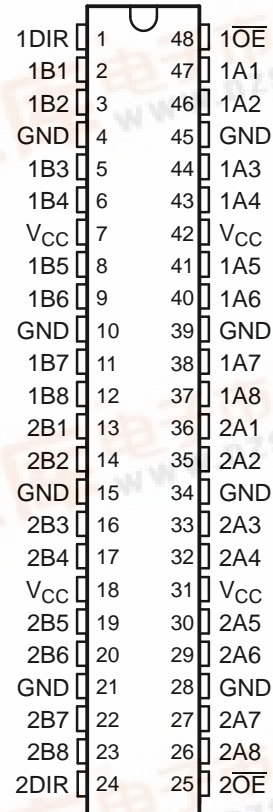
This 16-bit (dual-octal) noninverting bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16245 is designed for asynchronous communication between two data buses. The logic levels of the direction-control (DIR) input and the output-enable (\overline{OE}) input activate either the B-port outputs or the A-port outputs or place both output ports into the high-impedance mode. The device transmits data from the A bus to the B bus when the B-port outputs are activated, and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports is always active and must have a logic HIGH or LOW level applied to prevent excess I_{CC} and I_{CCZ} .

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

DGG, DGV, OR DL PACKAGE
(TOP VIEW)



SN74ALVCH16245 16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES015L–JULY 1995–REVISED NOVEMBER 2005

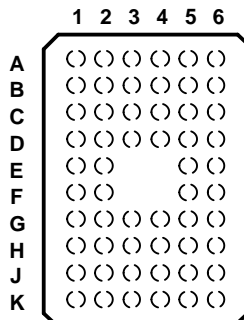


ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	FBGA – GRD	Tape and reel	SN74ALVCH16245GRDR	VH245
	FBGA – ZRD (Pb-free)		SN74ALVCH16245ZRDR	
	SSOP – DL	Tube	SN74ALVCH16245DL	ALVCH16245
		Tape and reel	SN74ALVCH16245DLR	
	TSSOP – DGG	Tape and reel	SN74ALVCH16245DGGR	ALVCH16245
			74ALVCH16245DGGRG4	
	TVSOP – DGV	Tape and reel	SN74ALVCH16245DGVR	VH245
			74ALVCH16245DGVRE4	
	VFBGA – GQL	Tape and reel	SN74ALVCH16245KR	VH245
			VFBGA – ZQL (Pb-free)	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

**GQL OR ZQL PACKAGE
(TOP VIEW)**

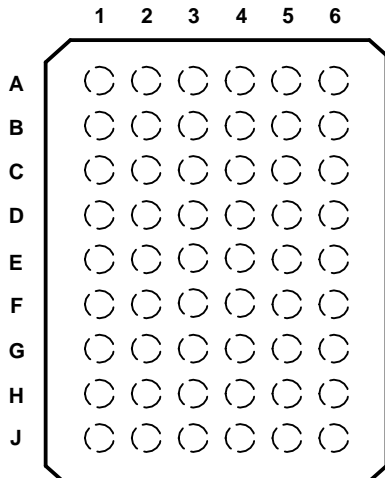


**TERMINAL ASSIGNMENTS⁽¹⁾
(56-Ball GQL/ZQL Package)**

	1	2	3	4	5	6
A	1DIR	NC	NC	NC	NC	1 \overline{OE}
B	1B2	1B1	GND	GND	1A1	1A2
C	1B4	1B3	V _{CC}	V _{CC}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
E	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
H	2B5	2B6	V _{CC}	V _{CC}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 \overline{OE}

(1) NC – No internal connection

**GRD OR ZRD PACKAGE
(TOP VIEW)**



**TERMINAL ASSIGNMENTS⁽¹⁾
(54-Ball GRD/ZRD Package)**

	1	2	3	4	5	6
A	1B1	NC	1DIR	1 \overline{OE}	NC	1A1
B	1B3	1B2	NC	NC	1A2	1A3
C	1B5	1B4	V _{CC}	V _{CC}	1A4	1A5
D	1B7	1B6	GND	GND	1A6	1A7
E	2B1	1B8	GND	GND	1A8	2A1
F	2B3	2B2	GND	GND	2A2	2A3
G	2B5	2B4	V _{CC}	V _{CC}	2A4	2A5
H	2B7	2B6	NC	NC	2A6	2A7
J	2B8	NC	2DIR	2 \overline{OE}	NC	2A8

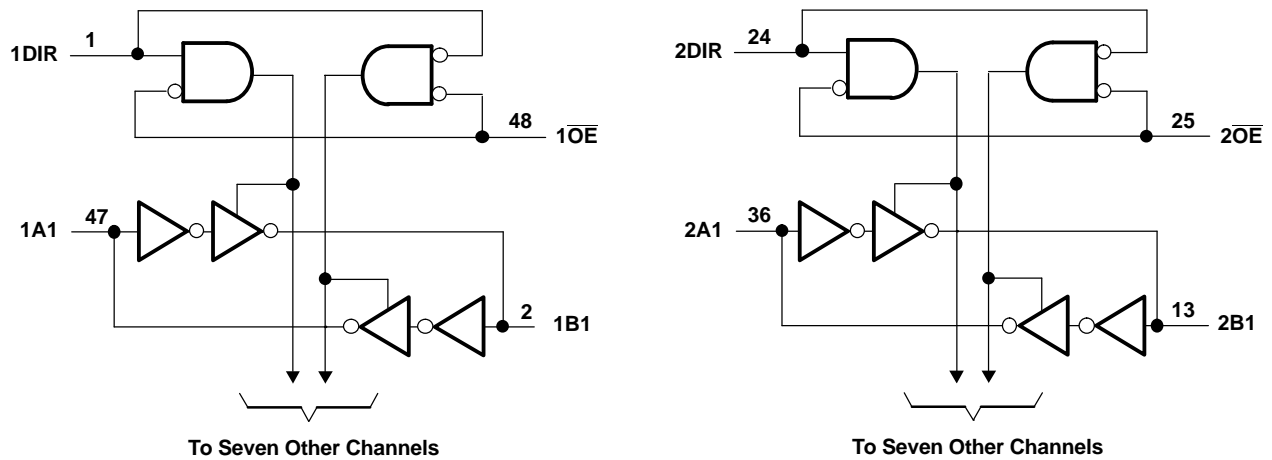
(1) NC – No internal connection

FUNCTION TABLE⁽¹⁾
(EACH 8-BIT SECTION)

CONTROL INPUTS		OUTPUT CIRCUITS		OPERATION
\overline{OE}	DIR	A PORT	B PORT	
L	L	Enabled	Hi-Z	B data to A bus
L	H	Hi-Z	Enabled	A data to B bus
H	X	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os always are active.

LOGIC DIAGRAM (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	4.6	V
V_I	Input voltage range ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
V_O	Output voltage range ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	-50	mA
I_{OK}	Output clamp current	$V_O < 0$	-50	mA
I_O	Continuous output current		± 50	mA
	Continuous current through each V_{CC} or GND		± 100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package	70	°C/W
		DGV package	58	
		DL package	63	
		GQL/ZQL package	42	
		GRD/ZRD package	36	
T_{stg}	Storage temperature range	-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

SN74ALVCH16245
16-BIT BUS TRANSCEIVER
WITH 3-STATE OUTPUTS



SCES015L–JULY 1995–REVISED NOVEMBER 2005

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage	1.65	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	1.7	
		V _{CC} = 2.7 V to 3.6 V	2	
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}	V
		V _{CC} = 2.3 V to 2.7 V	0.7	
		V _{CC} = 2.7 V to 3.6 V	0.8	
V _I	Input voltage	0	V _{CC}	V
V _O	Output voltage	0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 1.65 V	–4	mA
		V _{CC} = 2.3 V	–12	
		V _{CC} = 2.7 V	–12	
		V _{CC} = 3 V	–24	
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4	mA
		V _{CC} = 2.3 V	12	
		V _{CC} = 2.7 V	12	
		V _{CC} = 3 V	24	
Δt/Δv	Input transition rise or fall rate		10	ns/V
T _A	Operating free-air temperature	–40	85	°C

(1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}	I _{OH} = –100 μA	1.65 V to 3.6 V	V _{CC} – 0.2			V
	I _{OH} = –4 mA	1.65 V	1.2			
	I _{OH} = –6 mA	2.3 V	2			
	I _{OH} = –12 mA	2.3 V	1.7			
		2.7 V	2.2			
		3 V	2.4			
I _{OH} = –24 mA	3 V	2				
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V			0.2	V
	I _{OL} = 4 mA	1.65 V			0.45	
	I _{OL} = 6 mA	2.3 V			0.4	
	I _{OL} = 12 mA	2.3 V			0.7	
		2.7 V			0.4	
	I _{OL} = 24 mA	3 V			0.55	
I _I	V _I = V _{CC} or GND	3.6 V			±5	μA
I _{I(hold)}	V _I = 0.58 V	1.65 V		25		μA
	V _I = 1.07 V	1.65 V		–25		
	V _I = 0.7 V	2.3 V		45		
	V _I = 1.7 V	2.3 V		–45		
	V _I = 0.8 V	3 V		75		
	V _I = 2 V	3 V		–75		
	V _I = 0 to 3.6 V ⁽²⁾	3.6 V			±500	
I _{OZ} ⁽³⁾	V _O = V _{CC} or GND	3.6 V			±10	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V			40	μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μA
C _i	Control inputs V _I = V _{CC} or GND	3.3 V			4	pF
C _{io}	A or B ports V _O = V _{CC} or GND	3.3 V			8	pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 1.8 V	V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	B or A	(1)	1	3.7	3.6		1	3	ns
t _{en}	$\overline{\text{OE}}$	A or B	(1)	1	5.7	5.4		1	4.4	ns
t _{dis}	$\overline{\text{OE}}$	A or B	(1)	1	5.2	4.6		1	4.1	ns

(1) This information was not available at the time of publication.

SN74ALVCH16245

16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES015L–JULY 1995–REVISED NOVEMBER 2005



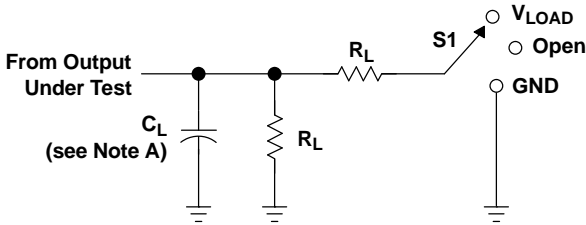
Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance	Outputs enabled	(1)	22	29	pF
		Outputs disabled	(1)	4	5	

(1) This information was not available at the time of publication.

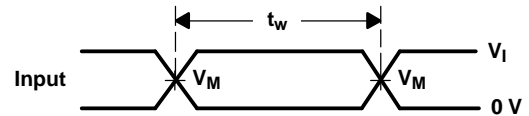
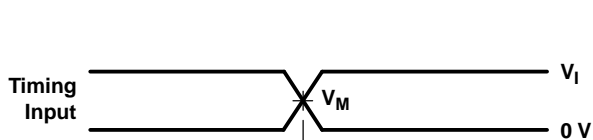
PARAMETER MEASUREMENT INFORMATION



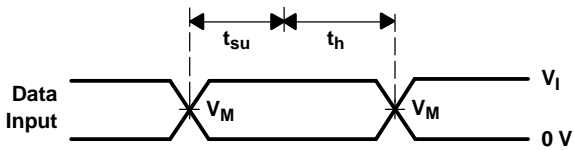
LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PHL}	GND

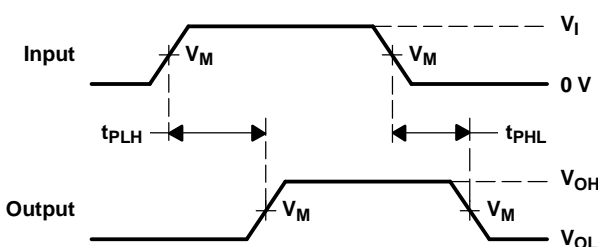
V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
1.8 V	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5 V \pm 0.2 V$	V_{CC}	≤ 2 ns	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3 V \pm 0.3 V$	2.7 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



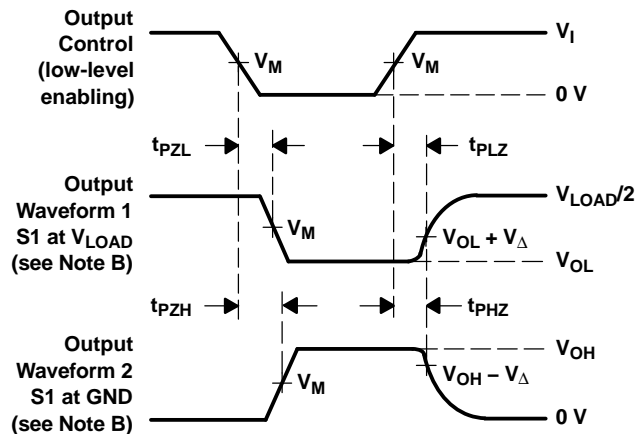
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
74ALVCH16245DGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16245DGVRE4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16245DLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16245GRDR	ACTIVE	BGA MICROSTAR JUNIOR	GRD	54	1000	TBD	SNPB	Level-1-240C-UNLIM
74ALVCH16245ZQLR	ACTIVE	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
74ALVCH16245ZRDR	ACTIVE	BGA MICROSTAR JUNIOR	ZRD	54	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM
SN74ALVCH16245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16245DGV	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16245KR	ACTIVE	BGA MICROSTAR JUNIOR	GQL	56	1000	TBD	SNPB	Level-1-240C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder

temperature.

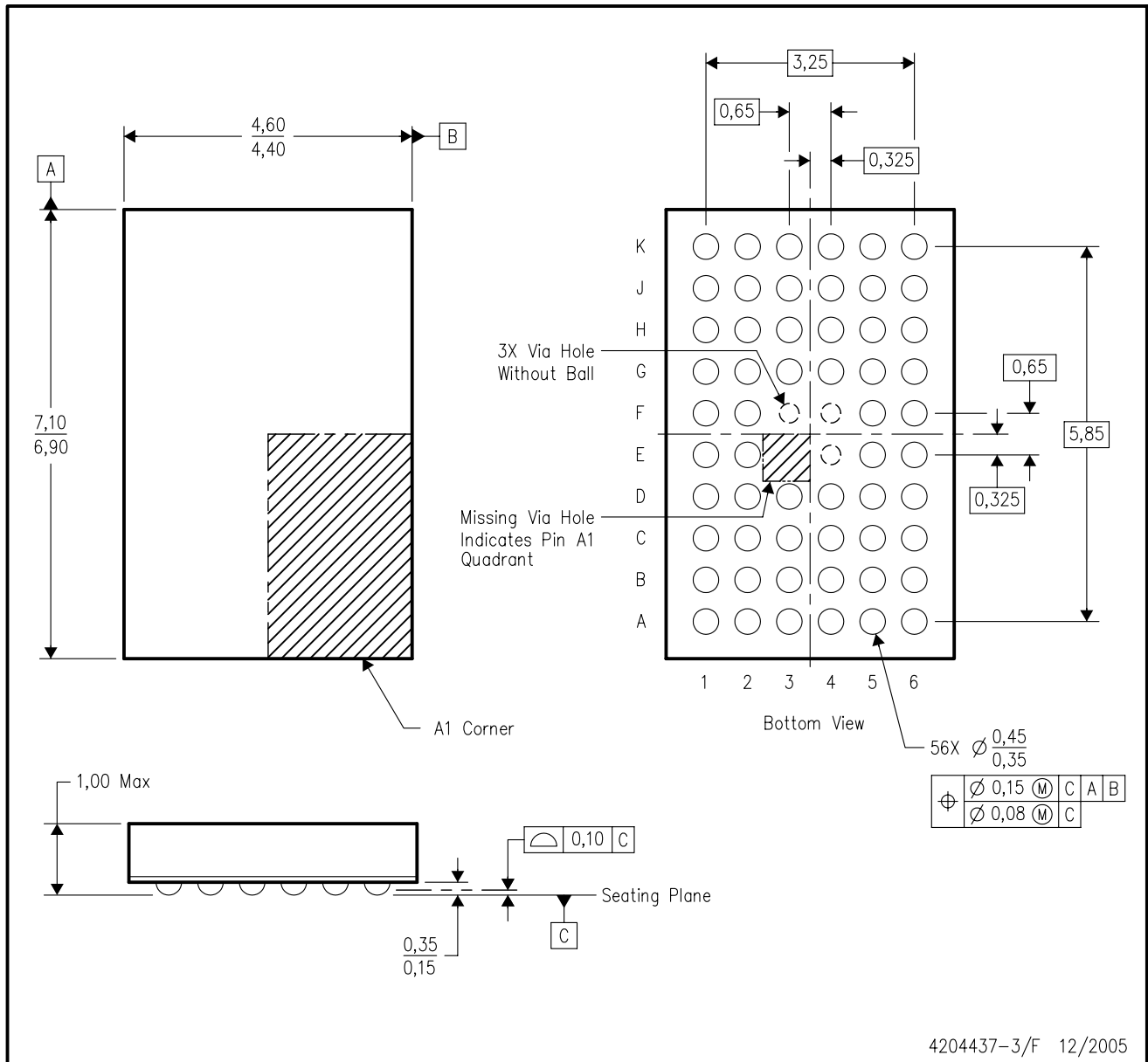
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MECHANICAL DATA

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY

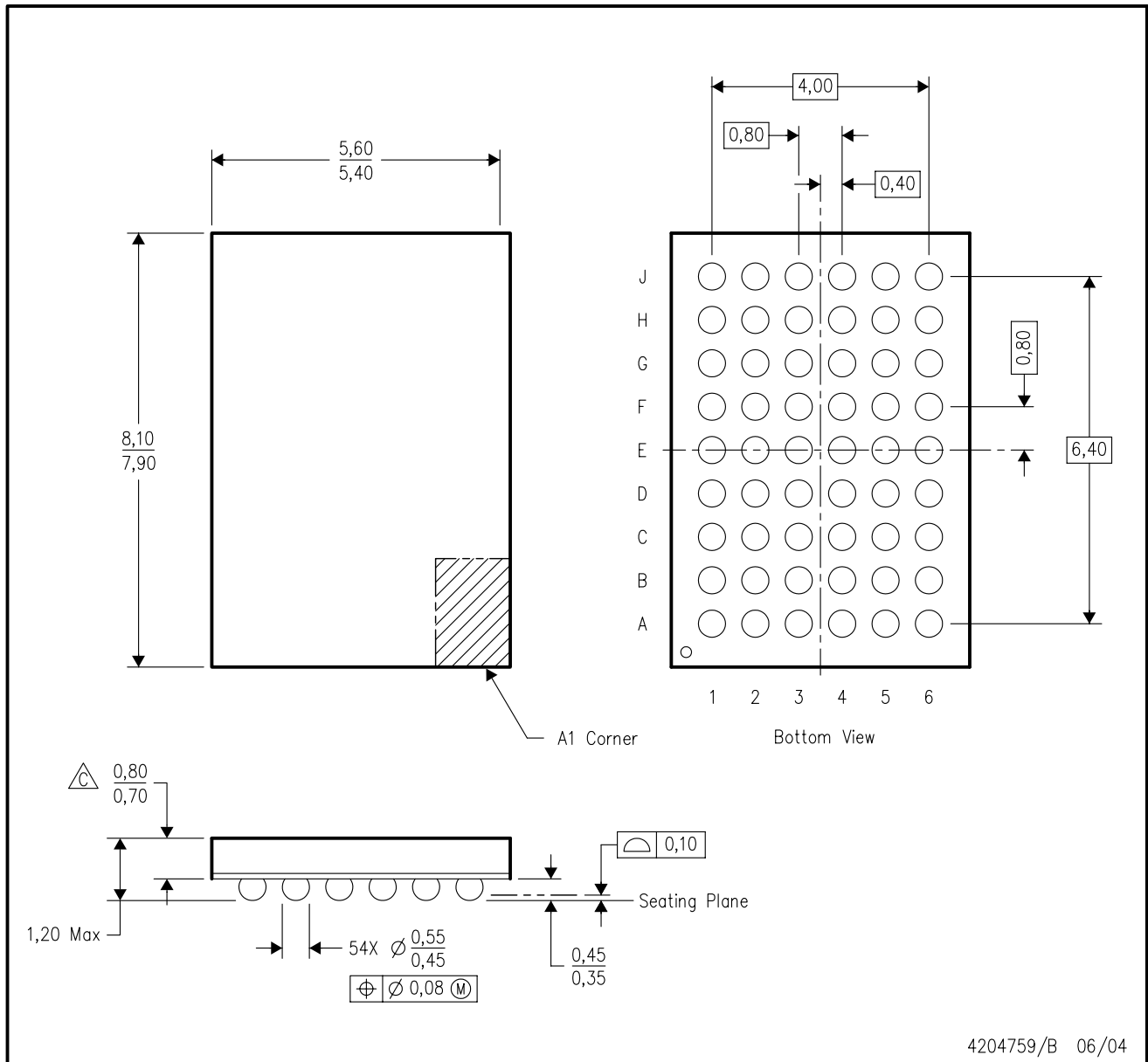


- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-225 variation BA.
 - D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).

MECHANICAL DATA

GRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



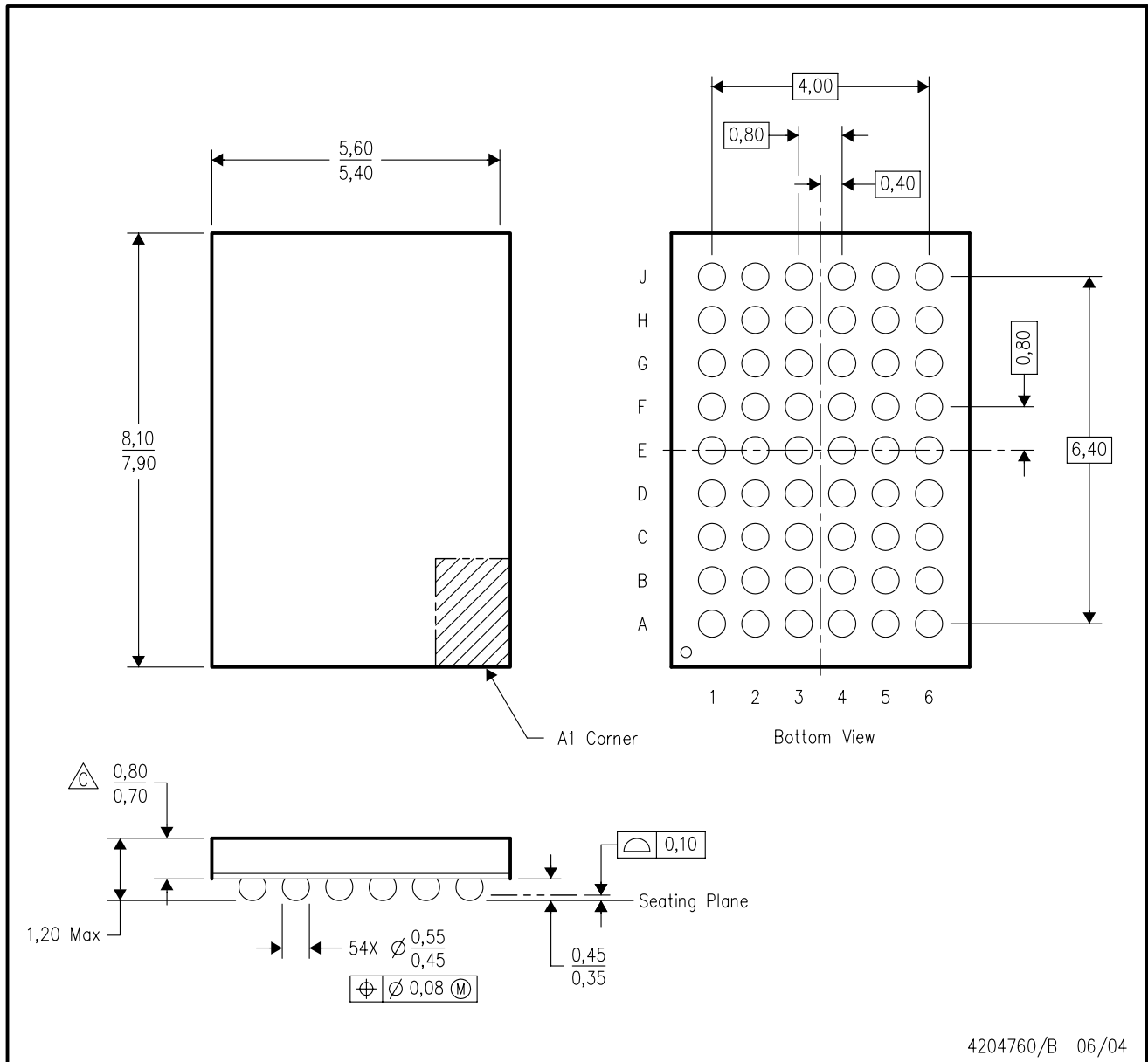
4204759/B 06/04

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-205 variation DD.
 - D. This package is tin-lead (SnPb). Refer to the 54 ZRD package (drawing 4204760) for lead-free.

MECHANICAL DATA

ZRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-205 variation DD.
 - D. This package is lead-free. Refer to the 54 GRD package (drawing 4204759) for tin-lead (SnPb).

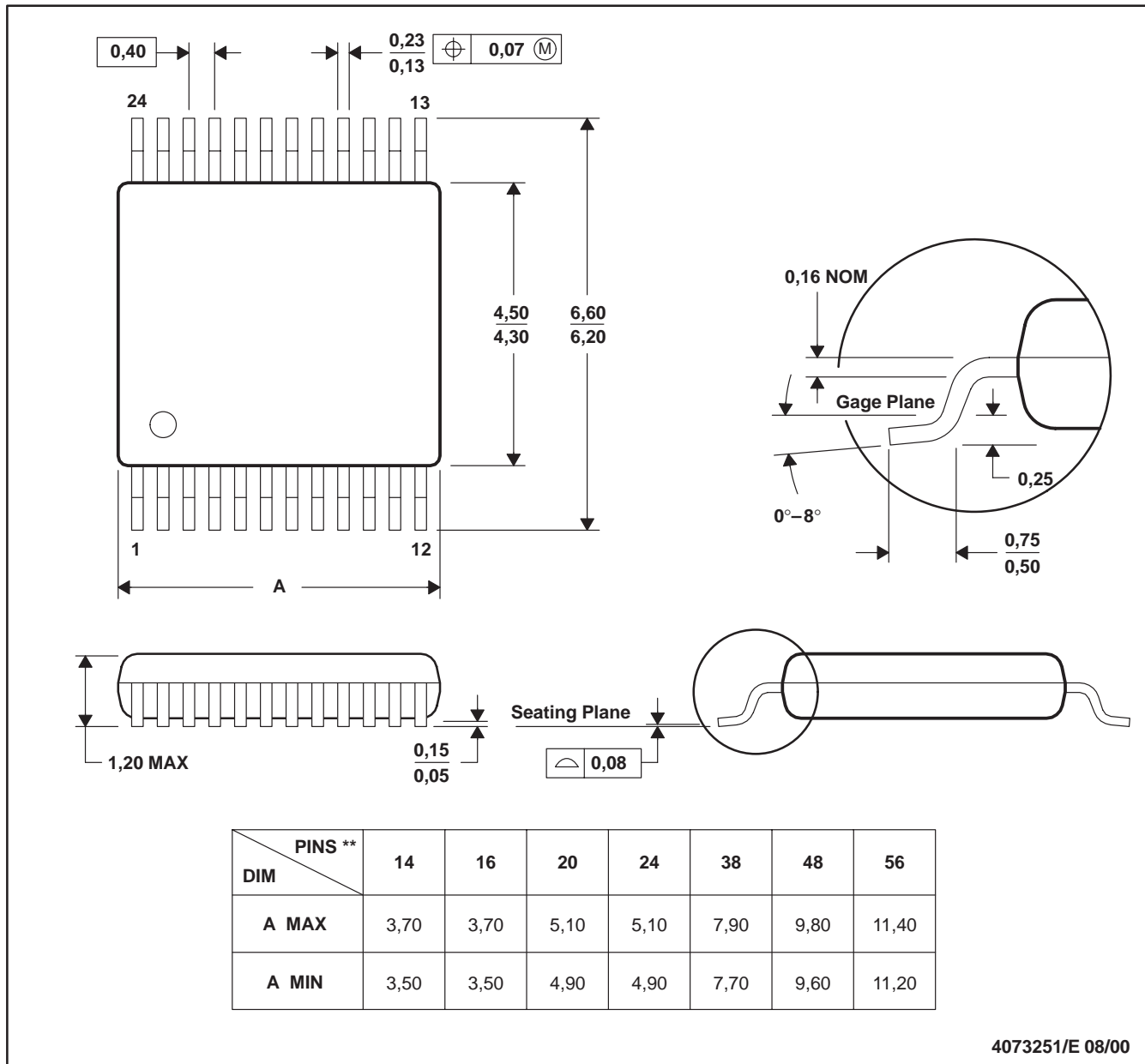
MECHANICAL DATA

MPDS006C – FEBRUARY 1996 – REVISED AUGUST 2000

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

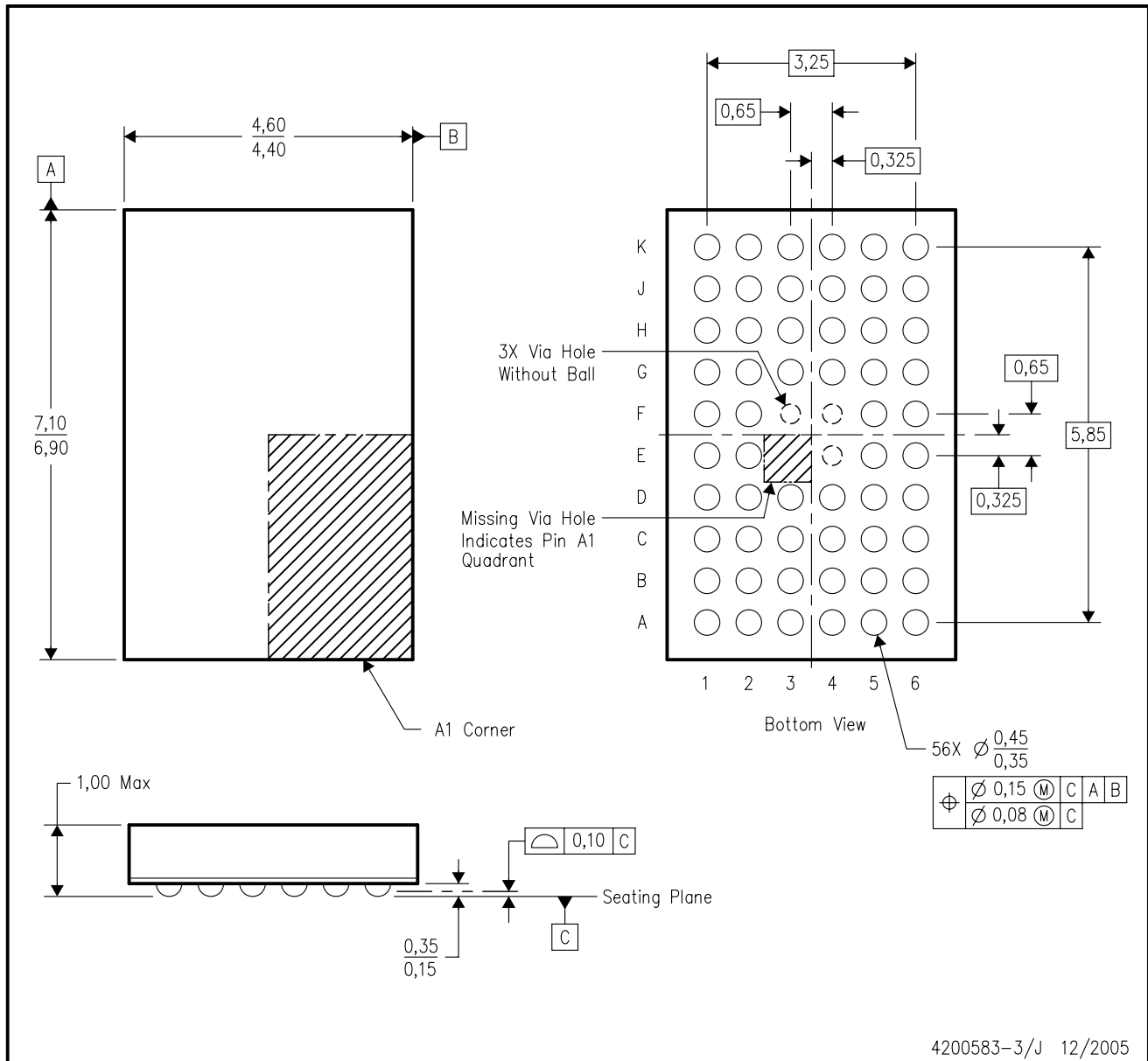


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

MECHANICAL DATA

GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-225 variation BA.
 - D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.

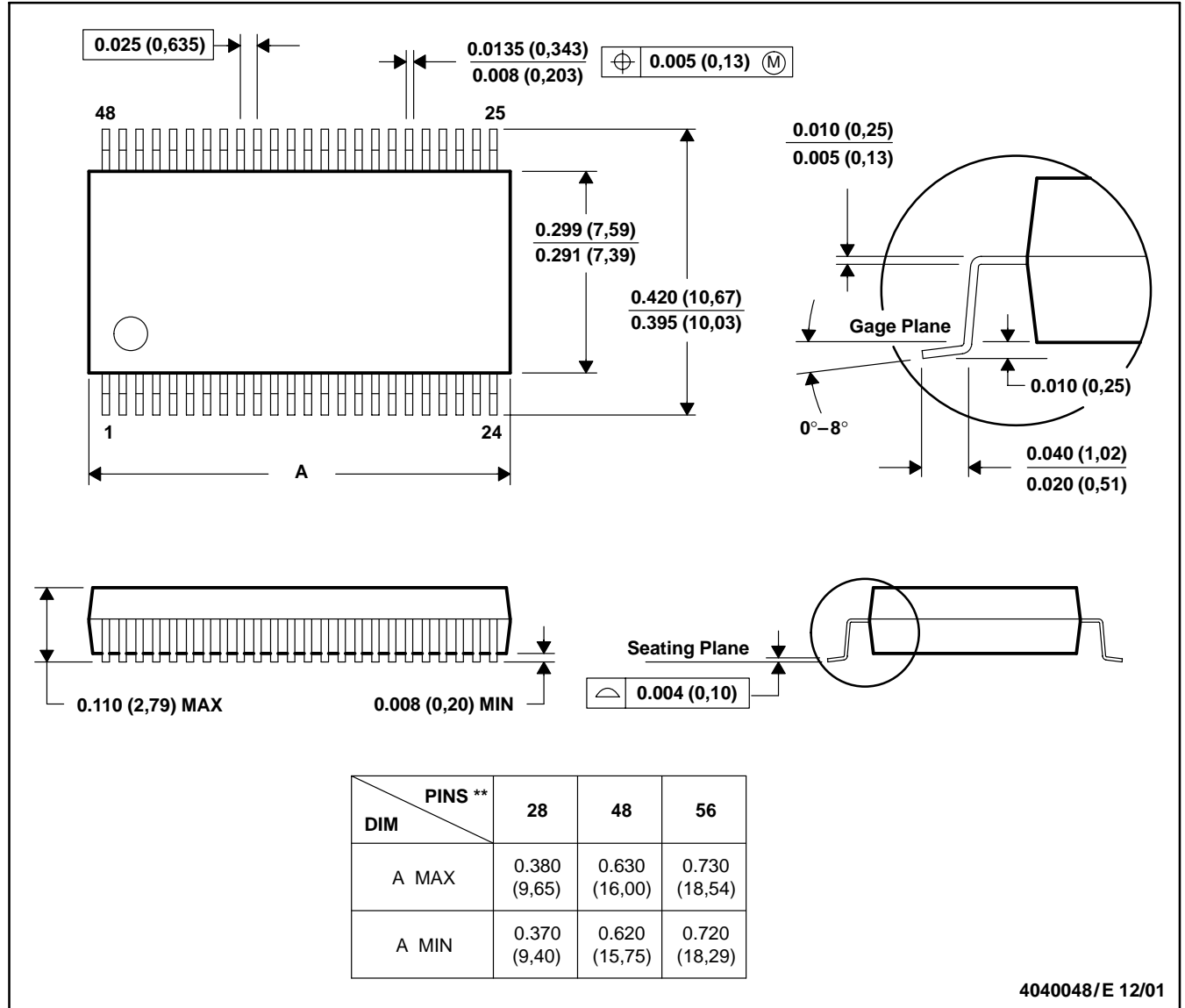
MECHANICAL DATA

MSS0001C – JANUARY 1995 – REVISED DECEMBER 2001

DL (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MO-118

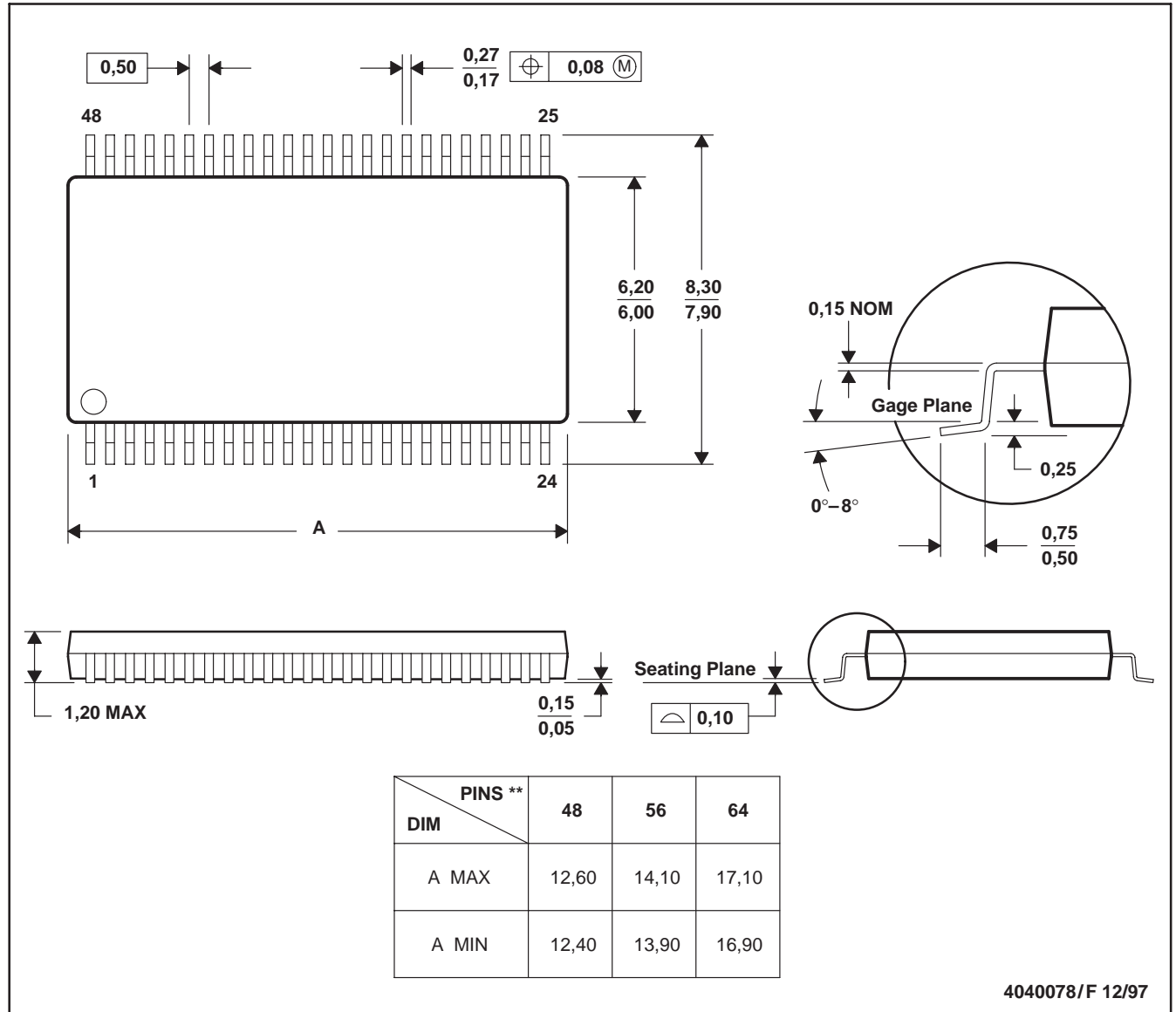
MECHANICAL DATA

MTSS003D – JANUARY 1995 – REVISED JANUARY 1998

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold protrusion not to exceed 0,15.
 - Falls within JEDEC MO-153

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